## WHAT IS CLAIMED IS:

A process for the wet chemical treatment of semiconductor wafers with treatment liquids, comprising the steps of

first $lac{1}{2}$ y treating the semiconductor wafers with an aqueous

HF solution;

then treating the semiconductor wafers with an aqueous  $O_3$  solution; and

then treating the semiconductor wafers with a liquid selected from the group consisting of water and an aqueous HCl solution;

whereby these treatment steps forming a treatment sequence  $\boldsymbol{B}_2\,.$ 

The process as claimed in claim 1,

wherein the treatment sequence  $B_2$  is preceded by a  $\begin{array}{c} S(\cdot) \\ \end{array}$  treatment  $B_1$  of the semiconductor wafers with an aqueous solution.

- 3. The process as claimed in claim 1, wherein the treatment sequence  $B_2$  is followed by a treatment  $B_3$  comprising drying the semiconductor wafers.
  - The process as claimed in claim 3,

is performed.

wherein the treatment of the semiconductor wafers is sequenced according to the term  $m^*\left(B_1\,+\,B_2\right)\,+\,B_3$ ,

m being an integer number and the treatment  $B_1$  and the treatment sequence  $B_2$  being carried out in succession, and this taking place m times, before the drying treatment  $B_3$ 

The process as claimed in claim 1,

wherein in treatment sequence  $B_2$ , the aqueous HF solution contains HF in a concentration of from 0.001% to 2% by weight and optionally HCl in a concentration of up to 2% by weight and optionally a surfactant; and

wherein all percents by weight are based upon the total solution weight.

- 6. The process as claimed in claim 1, wherein in treatment sequence  $B_2$ , the aqueous  $O_3$  solution contains  $O_3$  in a concentration of from 1 ppm to 30 ppm and is optionally exposed to megasonic waves.
  - 7. The process as claimed in claim 1,

wherein the treatment liquid used last in the treatment sequence  $B_2$  contains ozone and is optionally exposed to megasonic waves.

8. The process as claimed in claim 3,
wherein the drying treatment is carried out using a step
selected from the group consisting of centrifuging, using hot
water, using isopropanol, and using marangoni principle.

- 9. The process as claimed in claim 2,  $S(-1) = \frac{S(-1)}{S(-1)}$  wherein in treatment  $B_1$  the aqueous  $\frac{S(-1)}{A}$  solution contains a liquid selected from the group consisting of  $NH_4OH$  and  $H_2O_2$ , and TMAH (= tetramethylammonium hydroxide) and  $H_2O_2$ .
- 10. The process as claimed in claim 1, comprising carrying out each treatment with a treatment liquid in a bath.

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